

版次 (Ed)	变更摘要 (Change The Content)	日期 (Date)
0	新产品发行 (New Product Launch)	2017/09/06

序号 (NO.)	品名 (Name)	材质 (Material)
①	2.00 F型立式代WB胶芯 2.00 Pitch S/T Wire To Board Housing (H8-3)	LCP 本色 Natural
②	2.00 F型端子代WB端子 2.00 Pitch S/T Wire To Board Terminal (H8-2)	铜合金/表面镀锡 Copper Alloy/ Tin Plating
③	2.00 F型立式代WB焊片 2.00 Pitch S/T Wire To Board Fitting Nail (H8-3)	铜合金/表面镀锡 Copper Alloy/ Tin Plating
④	2.00 F型立式代WB胶盖 2.00 Pitch S/T Wire To Board Cover (H8-3)	LCP 本色 Natural

技术指标 (Technical Index):

1. 塑件表面应光洁、无毛边、无明显收缩、缺陷、裂纹等现象。
(The surface of the plastic parts should be smooth, no rough edges, no obvious shrinkage, defects, cracks and other phenomena)

2. 温度范围 (Temperature range): -40°C~85°C.

3. 额定电压 (Rated voltage): 200V, AC.

4. 接触电阻 (Contact resistance):

≤55mΩ (Initial) per contact, ≤25mΩ Change allowed.

5. 绝缘电阻 (Insulation resistance): ≥1000MΩ.

6. 产品料号 (Product material No.):

WT200FL—** *—2*

N0 0F CKT (产品PIN数)

Plating (电镀方式)

1: 端子全金
(Terminal G/F OVER ALL)

4: 端子全亮锡
(Terminal all bright tin)

20	接芯有LOGO/WD(housing with LOGO/WD)
2W	接芯无LOGO(housing without LOGO)

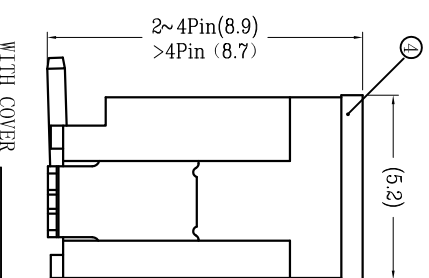
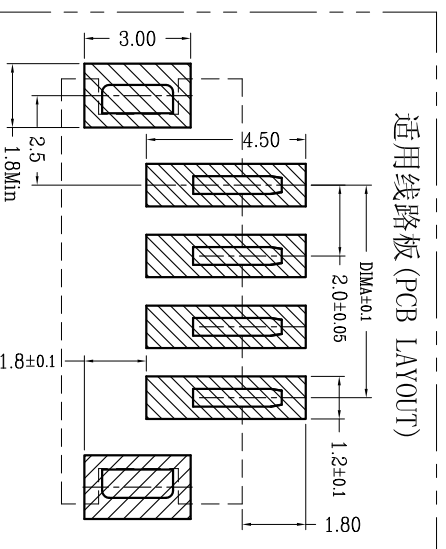
Packing (包装方式)

T: TUBE管装

R: TAPE & REEL 卷装

C: TAPE & REEL WITH COVER加吸盖卷装

适用线路板 (PCB LAYOUT)



WITH COVER

CKT	DIM A	DIM B	DIM C
2	2.00	4.90	8.00
3	4.00	6.90	10.00
4	6.00	8.90	12.00
5	8.00	10.90	14.00
6	10.00	12.90	16.00
7	12.00	14.90	18.00
8	14.00	16.90	20.00
9	16.00	18.90	22.00
10	18.00	20.90	24.00
11	20.00	22.90	26.00
12	22.00	24.90	28.00
13	24.00	26.90	30.00
14	26.00	28.90	32.00
15	28.00	30.90	34.00
16	30.00	32.90	36.00
17	32.00	34.90	38.00
18	34.00	36.90	40.00
19	36.00	38.90	42.00
20	38.00	40.90	44.00

深圳市虹成电子有限公司

品名 (TITLE) 2.00 Pitch F型立式2代WTB

2.00 PITCH H8.3 S/T WIRE TO BOARD SMT CONN.

料号 (DWGNO) HCZZ0398-5

比例 (SCALE) 1:1

一般公差 (TOLERANCE)
X ±.50 XX ±.10
X ±.20 XXX ±.05
ANGLES ±1°



审核 (APPD) 黄志明

校对 (CHKD) 王涛

张数 (SHEET) 1 Of 1
尺寸 (SIZE) A4
REV A